

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently amended) A semiconductor device, comprising:

a semiconductor chip;

multiple through electrodes formed in the semiconductor chip linking a front surface to a back surface thereof,

wherein said multiple through electrodes comprise a first through electrode and a second through electrode, and

wherein said first through electrode and said second through electrode have mutually differing cross-sectional areas in a common horizontal plane transverse to a through-hole direction; and

wherein at least one type of the through electrodes is contact through electrodes electrically connected to the semiconductor chip, and wherein at least one type of the through electrodes is non-contact through electrodes not electrically connected to the semiconductor chip.

2. (Canceled)

3. (Previously presented) A semiconductor device, comprising:

multiple through electrodes in a semiconductor chip linking a front surface to a back surface thereof,

wherein the through electrodes have mutually differing cross-sectional areas, and

wherein at least one type of the through electrodes is non-contact through electrodes not electrically connected to the semiconductor chip.

4. (Canceled)

5. (Original) The semiconductor device as set forth in claim 1, wherein the cross-sectional areas are increased according to a magnitude of an electric current via the through electrodes.

6. (Currently amended) The semiconductor device as set forth in claim ~~[[2]]~~ 1, wherein the cross-sectional areas are increased according to a magnitude of an electric current via the through electrodes.

7. (Original) The semiconductor device as set forth in claim 3, wherein the cross-sectional areas are increased according to a magnitude of an electric current via the through electrodes.

8. (Currently amended) The semiconductor device as set forth in claim ~~[[4]]~~ 1, wherein the cross-sectional areas are increased according to a magnitude of an electric current via the through electrodes.

9. (Original) The semiconductor device as set forth in claim 1, wherein the cross-sectional areas of those through electrodes which are connected to a ground terminal or a power

supply terminal of the semiconductor chip are greater than the cross-sectional areas of those through electrodes which are connected to a signal terminal.

10. (Currently amended) The semiconductor device as set forth in claim [[2]] 1, wherein the cross-sectional areas of those through electrodes which are connected to a ground terminal or a power supply terminal of the semiconductor chip are greater than the cross-sectional areas of those through electrodes which are connected to a signal terminal.

11. (Original) The semiconductor device as set forth in claim 3, wherein the cross-sectional areas of those through electrodes which are connected to a ground terminal or a power supply terminal of the semiconductor chip are greater than the cross-sectional areas of those through electrodes which are connected to a signal terminal.

12. (Currently amended) The semiconductor device as set forth in claim [[4]] 1, wherein the cross-sectional areas of those through electrodes which are connected to a ground terminal or a power supply terminal of the semiconductor chip are greater than the cross-sectional areas of those through electrodes which are connected to a signal terminal.

13. (Canceled)

14. (Currently amended) A chip-stack semiconductor device, comprising
multiple stacked semiconductor chips,

each of the semiconductor chips including multiple through electrodes therein linking a front surface to a back surface thereof,

wherein said multiple through electrodes comprise a first through electrode and a second through electrode, and

wherein:

the first and second through electrodes have mutually differing cross-sectional areas in a common horizontal plane transverse to a through-hole direction; and

at least one type of the through electrodes is contact through electrodes electrically connected to that semiconductor chip; and

wherein the cross-sectional areas are increased according to an interconnect line length through the multiple stacked semiconductor chips.

15. (Original) A chip-stack semiconductor device, comprising
multiple stacked semiconductor chips, each of the semiconductor chips including multiple through electrodes therein linking a front surface to a back surface thereof,
wherein:

the through electrodes have mutually differing cross-sectional areas; and

at least one type of the through electrodes is non-contact through electrodes not electrically connected to that semiconductor chip.

16. (Original) A chip-stack semiconductor device, comprising
multiple stacked semiconductor chips, each of the semiconductor chips including multiple through electrodes therein linking a front surface to a back surface thereof,

wherein:

the through electrodes have mutually differing cross-sectional areas;

at least one type of the through electrodes is contact through electrodes electrically connected to that semiconductor chip; and

at least one type of the through electrodes is non-contact through electrodes not electrically connected to that semiconductor chip.

17. (Canceled)

18. (Original) The chip-stack semiconductor device as set forth in claim 14, wherein the cross-sectional areas of those through electrodes which connect $n+1$ or more adjacent semiconductor chips are greater than the cross-sectional areas of those through electrodes which connect n adjacent semiconductor chips, where n is an integer more than or equal to 2.

19. (Original) The chip-stack semiconductor device as set forth in claim 15, wherein the cross-sectional areas of those through electrodes which connect $n+1$ or more adjacent semiconductor chips are greater than the cross-sectional areas of those through electrodes which connect n adjacent semiconductor chips, where n is an integer more than or equal to 2.

20. (Original) The chip-stack semiconductor device as set forth in claim 16, wherein the cross-sectional areas of those through electrodes which connect $n+1$ or more adjacent semiconductor chips are greater than the cross-sectional areas of those through electrodes which connect n adjacent semiconductor chips, where n is an integer more than or equal to 2.

21. (Previously presented) A chip-stack semiconductor device, comprising:
multiple stacked semiconductor chips, each of the semiconductor chips including
multiple through electrodes therein linking a front surface to a back surface thereof,
wherein the through electrodes have mutually differing cross-sectional areas, and
wherein the cross-sectional areas are increased according to an interconnect line length
through the multiple stacked semiconductor chips.

22. (Canceled)

23. (Original) The chip-stack semiconductor device as set forth in claim 15, wherein the
cross-sectional areas are increased according to an interconnect line length through the multiple
stacked semiconductor chips.

24. (Original) The chip-stack semiconductor device as set forth in claim 16, wherein the
cross-sectional areas are increased according to an interconnect line length through the multiple
stacked semiconductor chips.

25. (Original) The chip-stack semiconductor device as set forth in claim 21, wherein the
cross-sectional areas are increased in proportion to an interconnect line length through the
multiple stacked semiconductor chips.

26. (Currently amended) The chip-stack semiconductor device as set forth in claim [[22]]
14, wherein the cross-sectional areas are increased in proportion to an interconnect line length
through the multiple stacked semiconductor chips.

27. (Original) The chip-stack semiconductor device as set forth in claim 23, wherein the
cross-sectional areas are increased in proportion to an interconnect line length through the
multiple stacked semiconductor chips.

28. (Original) The chip-stack semiconductor device as set forth in claim 24, wherein the
cross-sectional areas are increased in proportion to an interconnect line length through the
multiple stacked semiconductor chips.

29. (Canceled)